



Fabrication of High Thermal Conductivity NARloy-Z-Diamond Composite Combustion Chamber Liner for Advanced Rocket Engines

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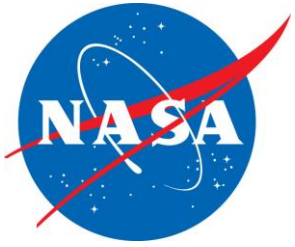
San Diego, CA



Materials and Processes Development Team



- NASA-MSFC
 - Biliyar Bhat – Principal Investigator
 - Sandra Greene – Co-Investigator – chamber design and testing
 - Enrique Jackson – thermal conductivity
 - James Coston, Ellen Rabenberg – microscopy
 - Will Tilson/Jacobs – tensile testing
 - Supported by NASA-MSFC Technology Investment Project
- NASA-GRC
 - Dr. David Ellis - consultant
- Penn State – Applied Research Laboratory
 - Dr. Jogender Singh – FAST processing
- Momentive Performance Materials
 - Aaron Rape – thermal conductivity
- Global Technology Enterprises
 - Dr. Sion Pickard – coated diamonds



Overview



- Introduction
- Improving thermal conductivity of copper alloys
- Project goals
- Chamber liner fabrication process
- Field Assisted Sintering Technology (FAST)
- Diffusion bonding
- Fabrication challenges
- Results
- Follow on work



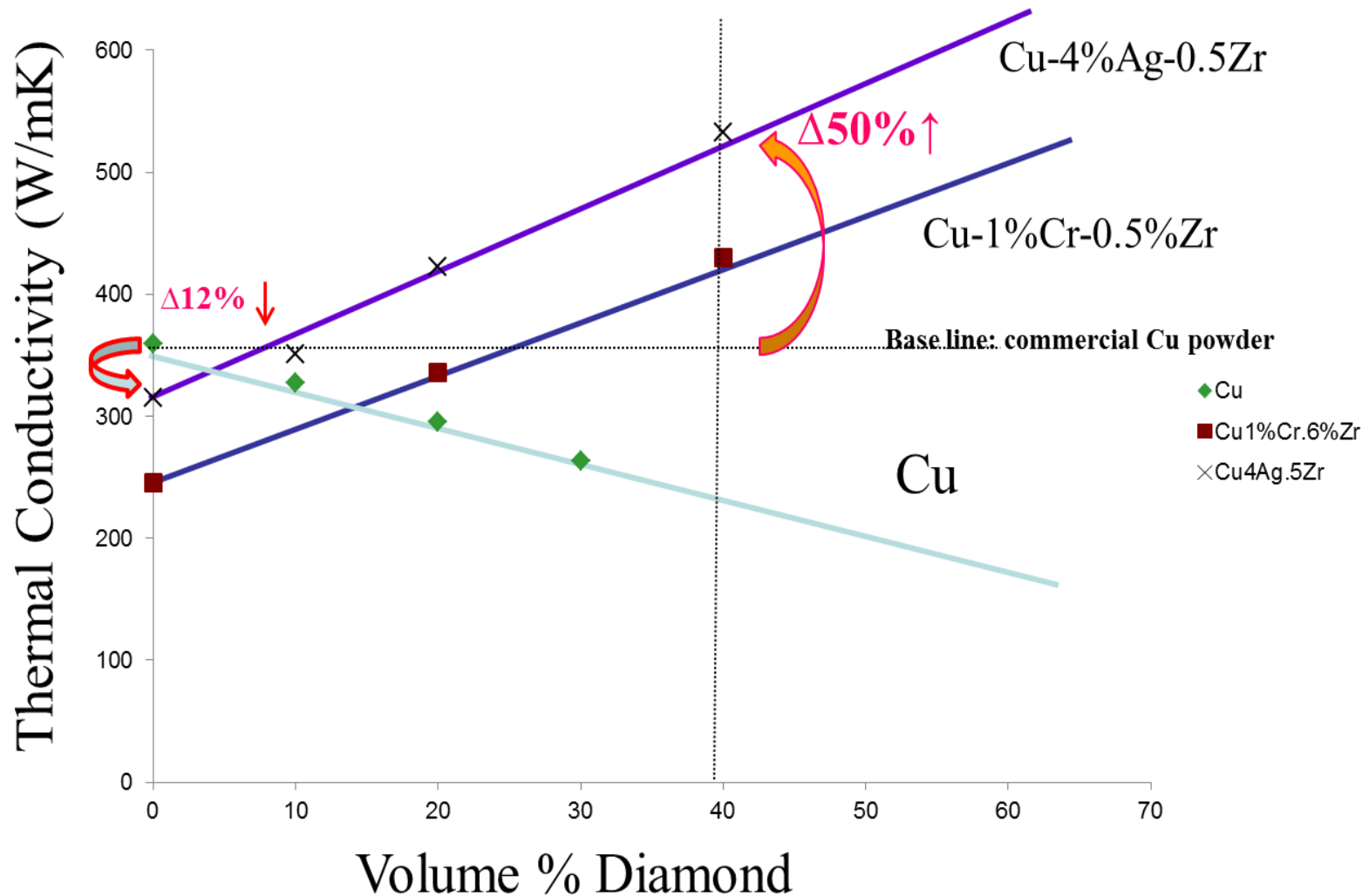
Introduction

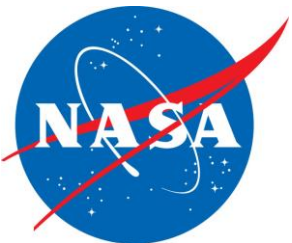


- NARloy-Z alloy (Cu-3Ag-0.5Zr) is state of the art material for making combustion chamber liner for liquid rocket engines. Thermal conductivity (TC)– 320 W/mK
 - Currently used in RS-25, RS-68
- Improved TC will help to improve the performance of rocket engines
 - Improved turbopump power, thrust to weight ratio, specific impulse
- Prior work on NARloy-Z-Diamond composites showed promise
 - 50% improvement in thermal conductivity relative to copper
- Technology development goals:
 - Fabricate a subscale combustion chamber liner (TRL 4)
 - Fabricate test chamber assembly
 - Hot fire test to demonstrate performance improvements (TRL 5)



Thermal conductivity of Cu-Ag-Zr-D composites





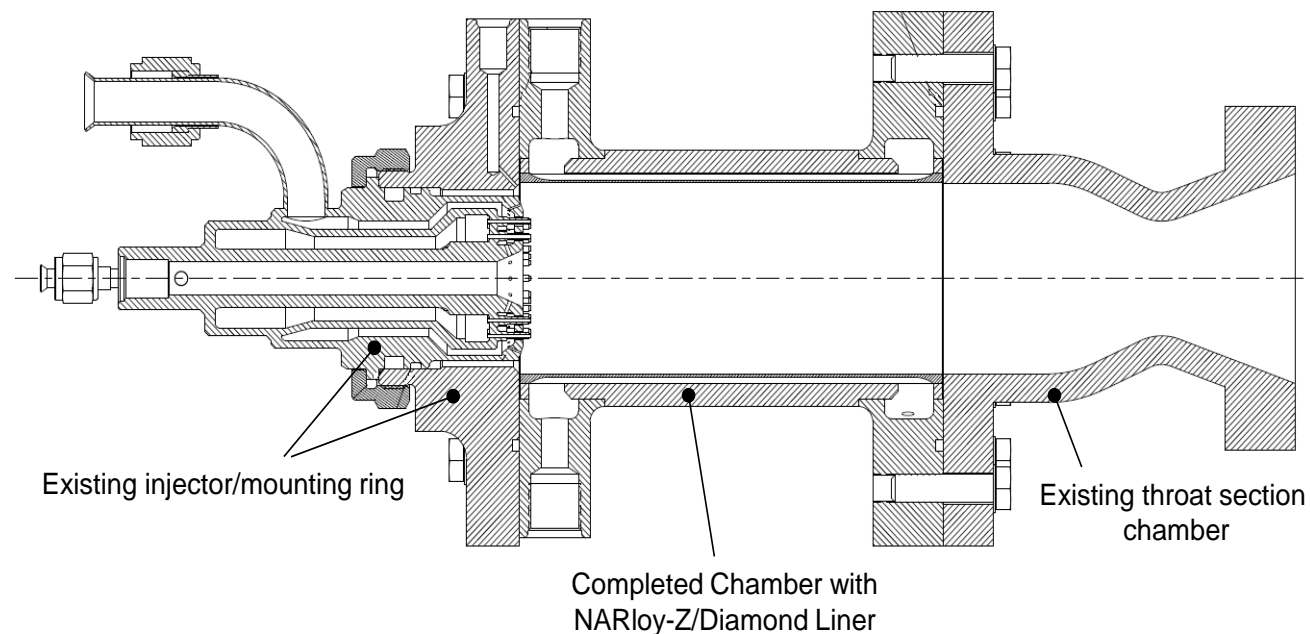
Combustion chamber liner, chamber assembly



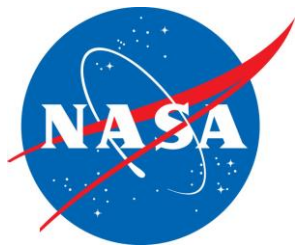
B

A

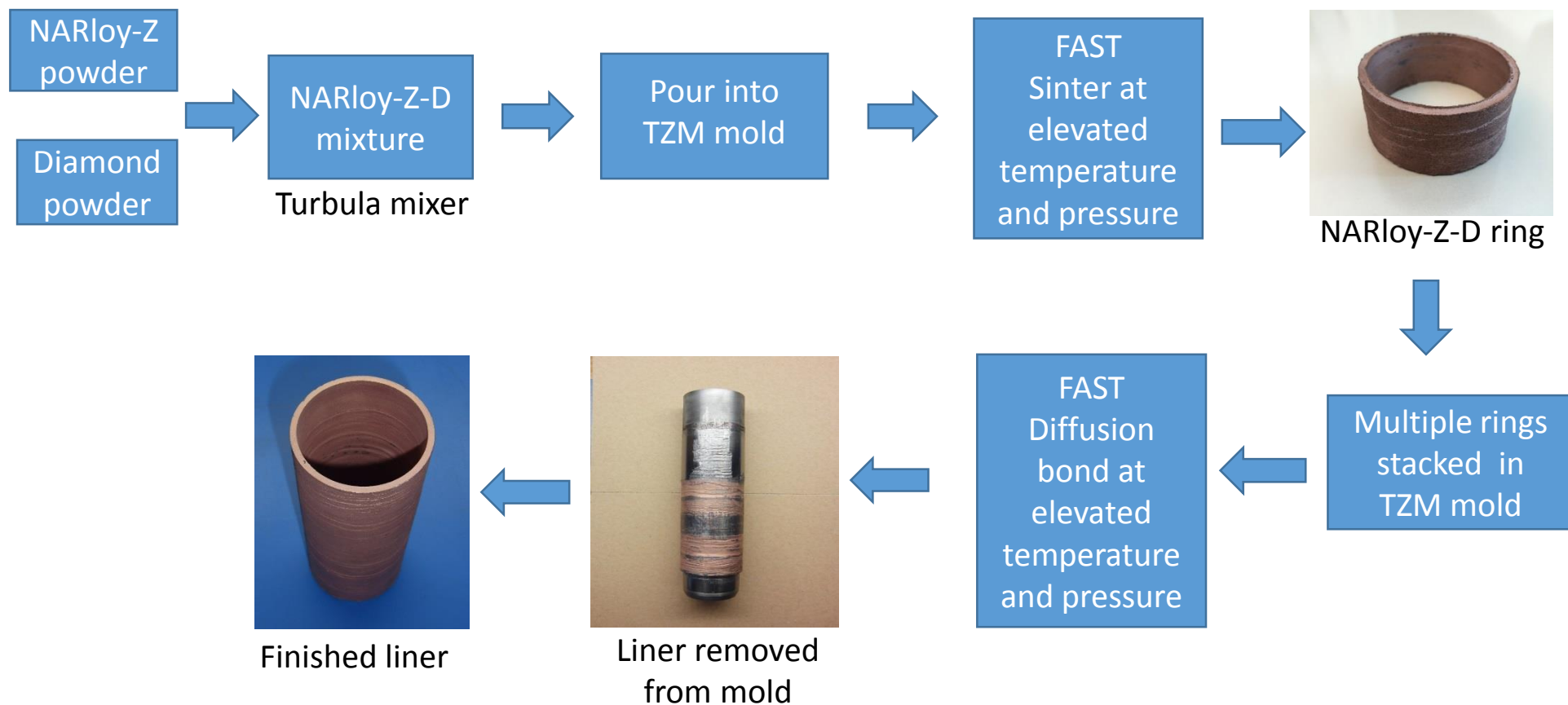
- Chamber liner (A) – 2.75"OD, 2.5" ID, 8" long
- Chamber assembly (B)

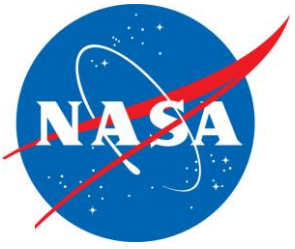


Hot fire test assembly schematic

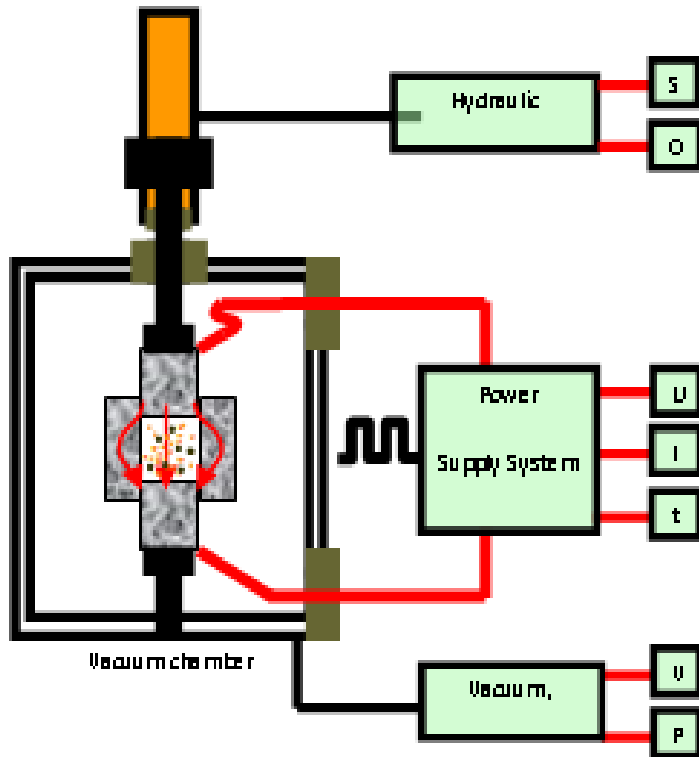


Chamber liner fabrication steps

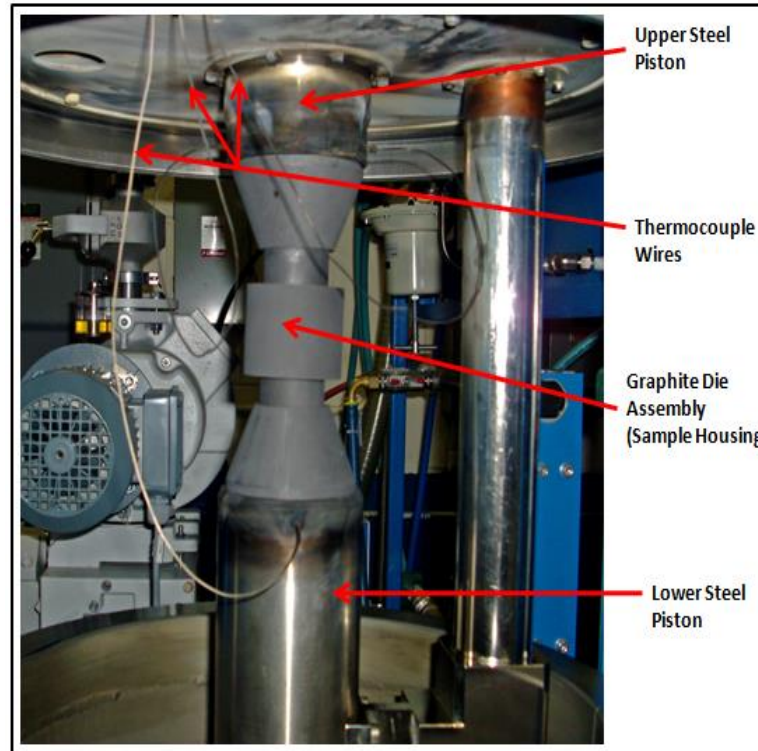




Field Assisted Sintering Technology (FAST)



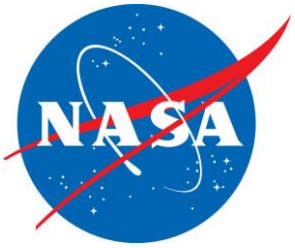
FAST - schematic



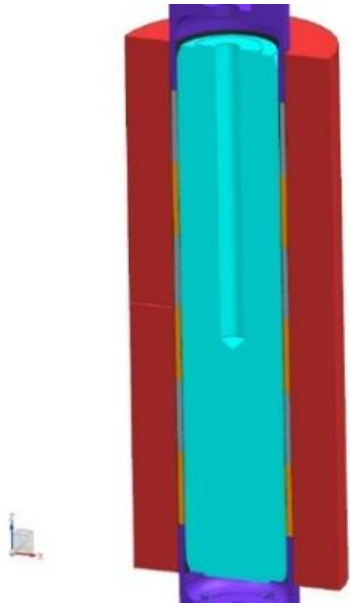
FAST system at Penn State - ARL



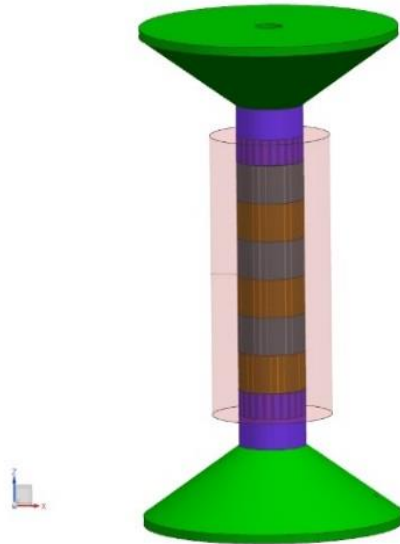
Sintering at high temperature in FAST apparatus



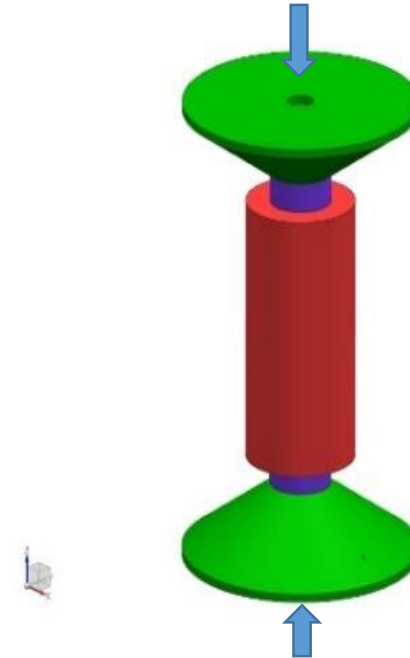
Diffusion bonding (schematic)



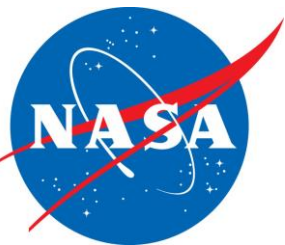
Eight rings stacked inside TZM mold for joining



Translucent model with multi-colors showing the rings



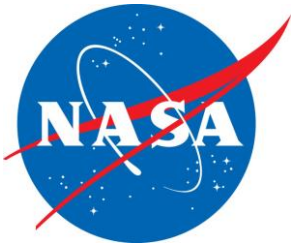
Diffusion bonding by FAST



Fabrication challenges



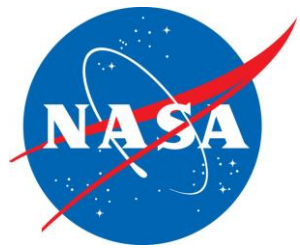
- Machining of NARloy-Z-D composite
 - Too hard to machine by conventional means
 - EDM and water jet cutting successful
- Near net shape forming
 - Switching from graphite to TZM molds for better strength at elevated temperatures
- Segregation of diamonds in microstructure
 - Diamonds segregate easily – hard to homogenize
 - Metal coatings help to improve mixing – Ti, Cu
 - Cu coating worked better
- Copper coated diamonds – supplied by GTE
 - Coating of MoC for better contact conductance
 - Overcoat of Cu for better mixing and sintering
- Diffusion bonding of NARloy-D rings
 - Interlayer of NARloy-Z for better bonding
- Microscopy and NDE
 - Material is too hard to make metallographic samples
 - Freshly fractured surfaces the best way to examine microstructure in SEM
 - CT scanning to assess segregation and ensure quality



Tensile properties (preliminary)



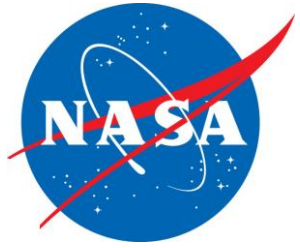
Sample type	Composition	Test temperature, Environment	YS, ksi	UTS, ksi	Elongation, %
NARloy-Z	Base line	75°F, air	18	45	33
NARloy-Z-30D	30 vol% diamond	75°F, air	19	19	<1
NARloy-Z-40D	40 vol% diamond	75°F, air	18-20	18-24	<1
NARloy-Z-40D	40 vol% diamonds	935°F, GN2	11	11	<1
NARloy-Z-30(Ti-D)	30 vol% Ti-coated diamond	75°F, air	12	12-13	<1
NARloy-Z-30 (Cu-MoC-D)	28 vol% diamonds, Cu-MoC coated	70°F, air	18	23	2-3
NARloy-Z-30 (Cu-MoC-D)	28 vol% diamonds, Cu-MoC coated	1000°F, 250 psi He	5-6	5-7	2-3
Diffusion bonded NARloy-Z-40D	40 vol.% Diamond; NARloy-Z at bond line	70°F, air	10	11	<1



Thermal conductivity (preliminary)

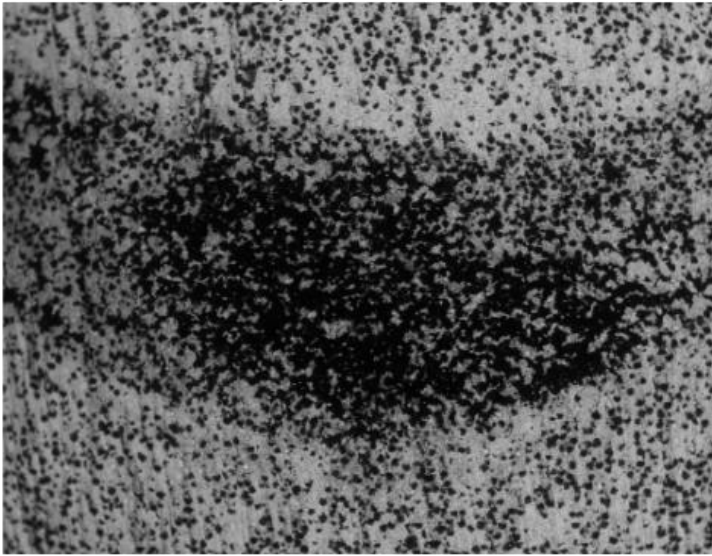


Sample chemistry (vol%)	Thermal conductivity (W/m-K)	Temperature, °K	Comments
NARloy-Z	320	300	Base line (Ref. 2)
NARloy-Z-30%D	337	380	Diamond segregation observed (Ref. 3)
NARloy-Z-40%D	344	380	Diamond segregation observed (Ref. 3)
NARloy-30%TiD	176	300	Ti lowers TC
NARloy-Z-28%CuD	462	300	TC acceptable

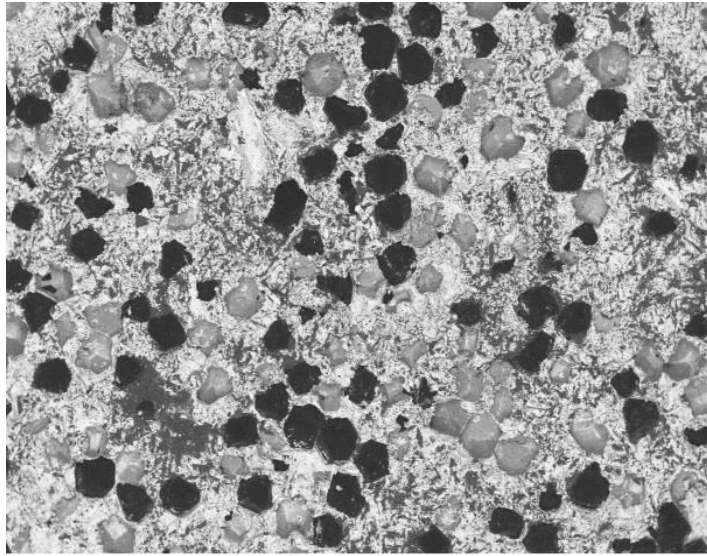


Microstructure

30 percent vf_c01_25x

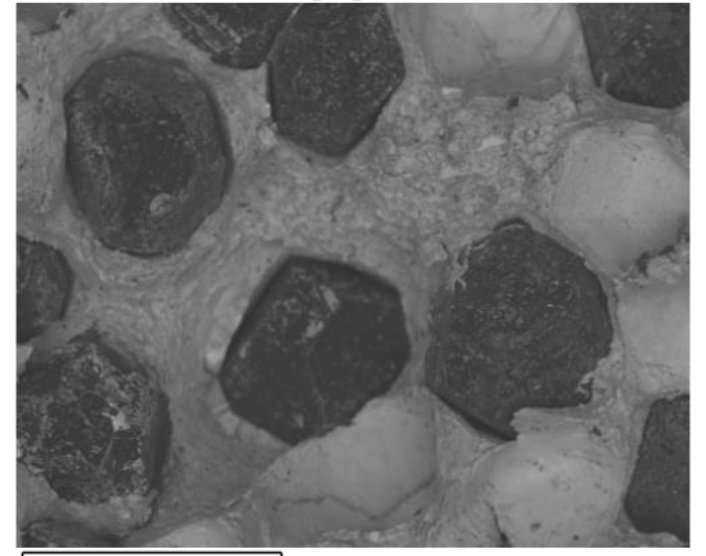


SEM Micrograph showing diamond segregation (dark area) in NARloy-Z-30%D Composite



SEM fractograph of NARloy-Z-Ti coated diamond composite

4_c02_100x



SEM fractograph of NARloy-Z-Cu-MoC coated diamond composite



Chamber liner



Chamber liner ring (2.5" ID., 2.75" OD, 1.0" long) made from NARloy-Z- CuD composite



NARloy-Z chamber liner fabricated by FAST - after taking out of the mold



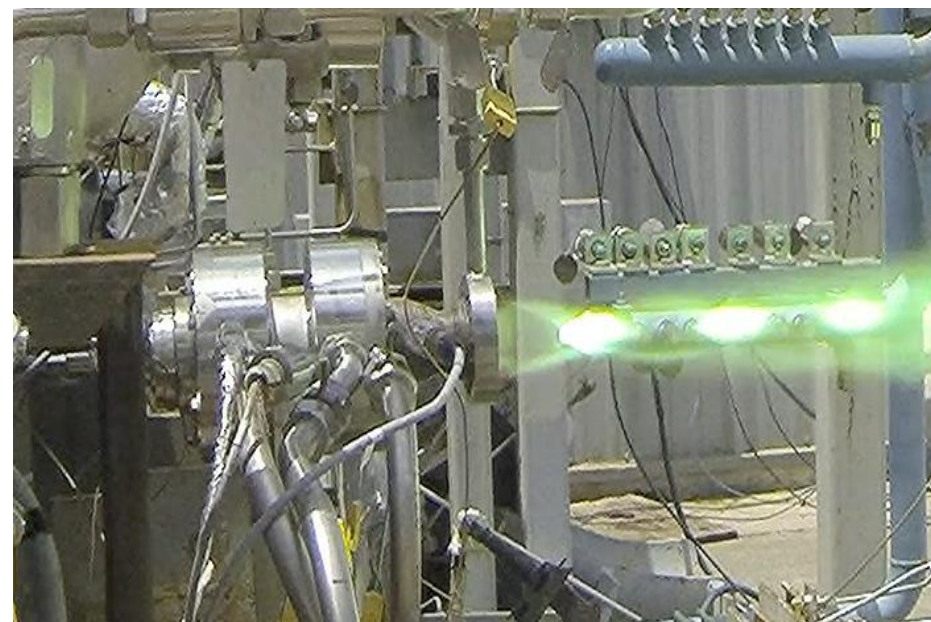
NARloy-Z chamber liner – after cleaning



Follow on work



- Diffusion bond NARloy-Z-CuD composite rings in FAST apparatus
- Machine cooling channels by water jet grinding
- Electroplate with nickel to close out the channels
- Fabricate coolant manifolds and integrate with hot fire test assembly
- Hot fire test in MSFC test stand 115
- Analyze data and assess performance



Hot fire testing at MSFC TS 115

Summary and Conclusions

- Successfully formulated a high thermal conductivity NARloy-Z-CuD composite material that can be processed into shapes.
- Developed processing technique for combustion chamber liner rings by use of Field Assisted Sintering Technology (FAST)
- Developed fabrication technique for chamber liner by diffusion bonding
- This is a break through technology in metal matrix composites, which will help to make our future propulsion systems lighter and higher performance using a high thermal conductivity material for combustion chamber liner.
- Materials and processing technologies can be developed further to optimize properties for specific applications, e.g., heat exchangers and other thermal management systems.